

innovators you can count on

## Materialise e-Stage 7.0 What's New



- Small UI changes
- Smarter point distribution algorithm
- DLP features

# materialise

### **Overview**



- Small UI changes
- Smarter point distribution algorithm
- DLP features



#### Gussets?

- Part-to-part connections
  - Green and yellow connections in Materialise Magics RP
- Parameters were added in the parameter file to be more flexible in creating gussets
- Previous versions created only gussets when no other solution was possible
- The new parameters can be used to force gussets

#### Benefits

- Reduce build time
- Reduce resin consumption







Old version

New version



Edit Parameter File										-		×
Coad 💾 Save as	💾 Save	ෆ Reset										2
											2	X
Machine				Top Connection				Grid				
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Recoater Load	5	N/m	າ 🕕	Contact Width			0	Edge Width	1	mm	<b>۳</b>	
Platform Shape	Rectangular	•	ຳ 🚺	Interior Point	0,15	mm	ຳ 🚺	Diamond Angle	45	•	n 🌔	
Build Envelope Minimum X	0	mm	r) 🚺	Border Point	0,25	mm	ຳ 🚺	Column Height To Width Ratio	7	7	۳ <b>(</b>	,
Build Envelope Minimum Y	0	mm	ຳ 🚺	Anchor Point	0,5	mm	ຳ 🚺	Hull reduction level			0	
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Sold Phase Density	1,3	kg/dm*	n 🚺	Contact Margin	0,2	mm	r) 🚺	Maximum Height	8	mm	<u>د</u>	2
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Gusset Preferences					
Gusset Preference Factor	0		<sup>ال</sup> ا		
Height Threshold	0	mm	<sup>ال</sup> ا		
Maximum Gusset Offset	0	n.w	ら ()		



#### Gusset preference factor

- A factor which reflects the amount of gussets versus the amount of connections to the platform
- The higher this value, the more gussets will be created

#### Height threshold

- A defined threshold z-height
- Above this z-height, gussets are preferred Below this z-height, gussets are not preferred
- Maximum gusset offset
  - The maximum overhang distance, expressed in number of diamonds, for which gussets are preferred



Gusset preferences

#### Small UI changes

- Smarter point distribution algorithm
- DLP features



## Small UI changes

#### ✓ 'Recoater Load' → 'Horizontal Top Load'

Machine					
Accuracy	0,1	mm	<b>۲)</b>		
Horizontal Top Load	5	N/m	<sup>ان</sup> ا		

#### ✓ 'STL input' & 'Slice output' → 'Slicing' parameters

Slicing			
Layer Thickness	0,125	mm	۳ 🕕
Slice Position	Тор 👻		ຳ 🚺
Sli Resolution	0	units/mm	ຳ 🕕
Cli Unit Size	0	mm	ຳ 🚺
SIc Force SUPPORT Type			ຳ 🚺



- Small UI changes
- **—** Smarter point distribution algorithm
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## Smarter point distribution

#### Fixed bug 'points in holes'



Loop implemented: points-grid-points



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## More platform connections possible (only with DLP license)



Platform connection dropdown	menu:
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Foundation: same as current feature for SLA

Platform Connection	Foundation -	]	<b>اں</b> ا
Maximum Height	8	mm	<b>اں</b> ا
Maximum Notch Height	4	mm	<b>اں</b> ا
Rigid Foundation Start			<b>اں</b>

Baseplate: to cope with the increased forces on the platform, a baseplate was added in the parameter file

Platform Connection	Baseplate -	]	າ 🚺
Baseplate Height	0,5	mm	ら 🚺
Baseplate Offset	0	mm	າ 🚺
Baseplate Margin	1,5	mm	ら 🕕

None: no additional platform connection will be generated

Platform Connection None

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#### Baseplate (only with DLP license)

Platform ConnectionBaseplateImage: Second sec

Height: the height of the baseplate

- Offset: by default the baseplate will reflect the hull of the grid. An extra offset can be applied to widen the baseplate
- Margin: a margin to keep between the baseplate and the part, when the latter is close to the platform









## How to create a baseplate?

#### Workflow:

- 1. Prepare platform in Materialise Magics
- 2. Export parts as STL (don't generate e-Stage supports!)
- 3. Open Materialise e-Stage standalone and browse to the folder where the STL parts are stored
- 4. Adapt parameter file in order to create base plate
- **5**. Click 'GO' in order to generate e-Stage and baseplate
- 6. Load e-Stage and baseplate STL files in Materialise Magics to check the result

## Parts can start straight from platform



- Previous versions didn't allow placing parts straight on the platform. This is now possible, since it's being used frequently in the DLP technology
- Only applicable if the chosen platform connection is 'baseplate' or '(none)'



## For more information, contact you local Materialise office.

*materialise.com/contact-locations*